

CMOS Dual Precision Monostable Multivibrator

High-Voltage Types (20-Volt Rating)

Features:

- Retriggerable/resettable capability
- Trigger and reset propagation delays
- independent of R_x, C_x
- Triggering from leading or trailing edge
- Q and Q buffered outputs available
- Separate resets
- Replaces CD4538B Type

CD14538B dual precision monostable multivibrator provides stable retriggerable/resettable one-shot operation for any fixed-voltage timing application.

An external resistor (R_x) and an external capacitor (C_x) control the timing and accuracy for the circuit. Adjustment of R_x and C_x provides a wide range of output pulse widths from the Q and Q terminals. The time delay from trigger input to output transition (trigger propagation delay) and the time delay from reset input to output transition (reset propagation delay) are independent of R_x and C_x . Precision control of output pulse widths is achieved through linear CMOS techniques.

Leading-edge-triggering (+TR) and trailing-edge-triggering (-TR) inputs are provided for triggering from either edge of an input pulse. An unused +TR input should be tied to V_{ss}. An unused -TR input should be tied to V_{pD}. A RESET (on low level) is provided for immediate termination of the output pulse or to prevent output pulses when power is turned on. An unused RESET input should be tied to V_{pD}. However, if an entire section of the CD14538B is not used, its inputs must be tied to either V_{pD} or V_{ss}. See Table I.

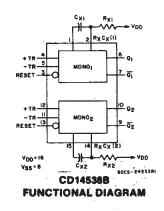
In normal operation the circuit retriggers (extends the output pulse one period) on the application of each new trigger pulse. For operation in the non-retriggerable mode, \overline{Q} is connected to -TR when leading-edge triggering (+TR) is used or Q is connected to +TR when trailing-edge triggering (-TR) is used. The time period (T) for this multivibrator can be calculated by: T = R_xC_x.

The minimum value of external resistance, R_x , is 4 K Ω . The minimum and maximum values of external capacitance, C_x , are 0 pF and 100 μ F, respectively.

The CD14538B is interchangeable with type MC14538 and is similar to and pin-compatible with the CD4098B* and CD4538B. It can replace the CD4538B which type is not recommended for new designs.

The CD14538B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

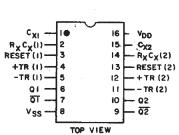
*T = 0.5 R_xC_x for $C_x \ge 1000 \text{ pF}$ #T = R_xC_x ; $C_xmin = 5000 \text{ pF}$



- Wide range of output-pulse widths
- Schmitt-trigger input allows unlimited
- rise and fall times on +TR and -TR inputs 100% tested for maximum quiescent current at 20 V
- Maximum input current of 1 µA at 18 V over
- full package-temperature range; 100 nA at 18 V and 25° C
- Noise margin (full package-temperature range):
 - $1 V at V_{DD} = 5 V$
 - 2 V at V_{DD} = 10 V
 - 2.5 V at Vpp = 15 V
- 5-V, 10-V, and 15-V parametric ratings
- Standardized. symmetrical output characteristics
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices."

Applications:

- Pulse delay and timing
- Pulse shaping



TERMINALS 1,8,15 ARE ELECTRICALLY CONNECTED INTERNALLY 92CS-24 848RI

Terminal Assignment

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (VDD)	
Voltages referenced to V _{SS} Terminal)	
INPUT VOLTAGE RANGE, ALL INPUTS	+0.5V to V-0.5V to V-0.5V
DC INPUT CURRENT, ANY ONE INPUT	+10mA
POWER DISSIPATION PER PACKAGE (PD):	
POWER DISSIPATION PER PACKAGE (P _D): For $T_A = -55^{\circ}C$ to $+100^{\circ}C$. For $T_A = +100^{\circ}C$ to $+125^{\circ}C$. Dente Linearity Dente Dissipation PER PACKAGE (P _D): The second	500mW
For T _A =+100°C to +125°C	y at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	and the second
FOR T _A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	100mW
OPERATING-TEMPERATURE RANGE (T _A)	55°C to +125°C
STORAGE TEMPERATURE RANGE (Tstg)	65°C to +150°C
LEAD TEMPERATURE (DURING SOLDĚRING):	f
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max	+265 ⁰ C

RECOMMENDED OPERATING CONDITIONS For maximum reliability, nominal operating conditions should be selected so that operating is always within the following ranges:

CHARACTERISTIC			VDO	LIN	UNITS	
Chanactenistic				Min.	Max.	UNITS
Supply-Voltage Range (For T _A =Full Package-Temp	erature Range)			3	18	y
Input Pulse Width +TR, -TR, or RESET	twn, twL		5 10	140 80		ns
· ·			15	60		

FUNCTIION	V _{DD} TO TERM. NO.		1	TO 1. NO.	1 '	PULSE	OTHER CONNECTIONS	
	MONO1	MONO ₂	MONO	MONO ₂	MONO1	MONO2	MONO1	MONO ₂
Leading-Edge Trigger/ Retriggerable	3, 5	11, 13			4	12		
Leading-Edge Trigger/ Non-Retriggerable	3	13		с. - с. - м. ч.	4	12	5-7	11-9
Trailing-Edge Trigger/ Retriggerable	3	. 13	4	12	5	° 11		
Trailing-Edge Trigger/ Non-Retriggerable	3	13			5	11	4-6	12-10

TABLE I CD4538B FUNCTIONAL TERMINAL CONNECTIONS

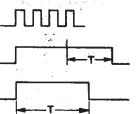
NOTES:

1. A RETRIGGERABLE ONE-SHOT MULTIVIBRATOR HAS AN OUTPUT PULSE WIDTH WHICH IS EXTENDED ONE FULL TIME PERIOD (T) AFTER APPLICATION OF THE LAST TRIGGER PULSE.

- 2. A NON-RETRIGGERABLE ONE-SHOT MULTIVIBRATOR HAS A TIME PERIOD (T) REFERENCED FROM THE APPLI-CATION OF THE FIRST TRIGGER PULSE.
- RETRIGGERABLE MODE PULSE WIDTH (+TR MODE)

INPUT PULSE TRAIN

NON-RETRIGGERABLE MODE PULSE WIDTH (+TR MODE)



COMMERCIAL CMOS HIGH VOLTAGE ICS

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STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	co	NDITIO	NS	LIN							UNITS
	V ₀ (V)	V _{IN} (V)	V _{DD} (V)	-55	-40	+85	+125	Min.	+25 Typ.	Max.	
		0,5	5	5	5	150	150	-	0.04	5	
Quiescent Device	_	0,10	10	10	10	300	300	-	0.04	10	1.
Current, I _{DD} Max.	-	0,15	15	20	20	600	600	-	0.04	20	μA
	-	0,20	20	100	100	3000	3000	-	0.08	100	
Output Low (Sink)	0.4	0,5	5.	0.64	0.61	0.42	0.36	0.51	1	—	1
Current, IoL Min.	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	1
Current, IoL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-	1
Output High (Source) Current, I _{он} Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1		mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2		1
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	1
Output Voltage:	—	0,5	5		0.	05		—	0	0.05	1
Low-Level, Vol Max.	—	0,10	10		0.	05		—	0	0.05	1
	-	0,15	15		0.	05		- 1	0	0.05	1
Output Voltage:	—	0,5	5	4.95 4.95					5	—	
High-Level, Von Min.	—	0,10	10		9.	95		9.95	10	_	- ×
Thys-Level, YOH With.	—	0,15	15		14	.95	15	_	1.		
Input Low Voltage,	0.5,4.5	-	5		1	.5		—		1.5	
VIL Max.	1,9	<u> </u>	10		:	3		—	-	3	1
VIL MAX.	1.5,13.5	—	. 15		4	1				4	1 v
Input High Voltage, Vie Min.	0.5,4.5		5		3	5		. 3.5	—	-] *
	1,9		10		1	7		7		_]
a 164 tattti.	1.5,13.5	_	15	11 11					—	-]
Input Current, I _{IN} Max.	-	0,18	18	±0.1	±0.1	±1	±1	—	±10 ⁻⁵	±0.1	μA

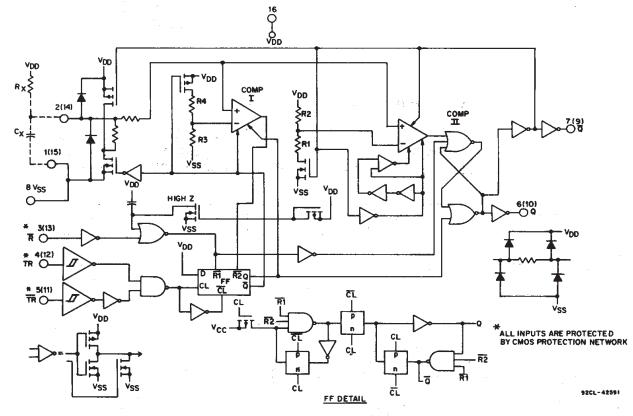
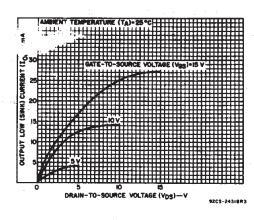


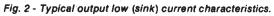
Fig. 1 - Logic diagram (½ of device shown).

CHARACTERISTIC		TEST CONDITIONS		LIMITS		
CHARACTERISTIC			Min.	Тур.	Max.	UNITS
Transition Time	ttin, tthe	5	_	100	200	1
		10	_	50	100	
		15	_	40	80	
Propagation Delay Time:	telh, tehl	5	_	300	600	1
+TR or -TR to Q or Q		10	-	150	300	
		15	_	100	220	ns
Reset to Q or Q		5		250	500]
		10	-	125	250	
		15		95	190	
Minimum Input Pulse Width:	tw∺, tw∟	5	-	80	140	1
+TR, -TR or Reset		10	-	40	80	
		15		30	60	1
Output Pulse Width - Q or Q:	Τ.	5	198	210	230	
C _x = 0.002 μF, R _x = 100 KΩ		10	200	212	232	μs
		15	202	214	234	
C _x =0.1 μF, R _x =100 KΩ		5	9.4	9.97	10.5	
	: :	10	9.4	9.95	10.6	ms
· · ·		15	9.5	10	10.6	
C _x =10 μF, R _x =100 KΩ		5	0.95	1	1.06	
		10	0.95	1	1.06	s
		15	0.96	1.01	1.07	
Pulse Width Match between	100 (T ₁ -T ₂)	5	-	±1		
circuits in same package:	T	10	-	±1	-	%
C _x =0.1 μF, R _x =100 KΩ	Τ1	15	-	±1	_	
Minimum Retrigger Time	t _{er}	5	0		_	
		10	0	-	. –	ns
		15	0		-	
Input Capacitance	Cin	Any Input		5	7.5	pF

DYNAMIC ELECTRICAL CHARACTERISTICS, At TA=25°C; Input tr,tr=20 ns, CL=50 pF

*Note: Minimum R_x value=4 KΩ, minimum C_x value=5000 pF.





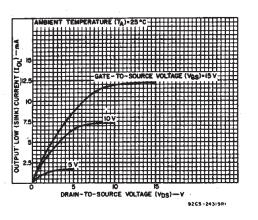
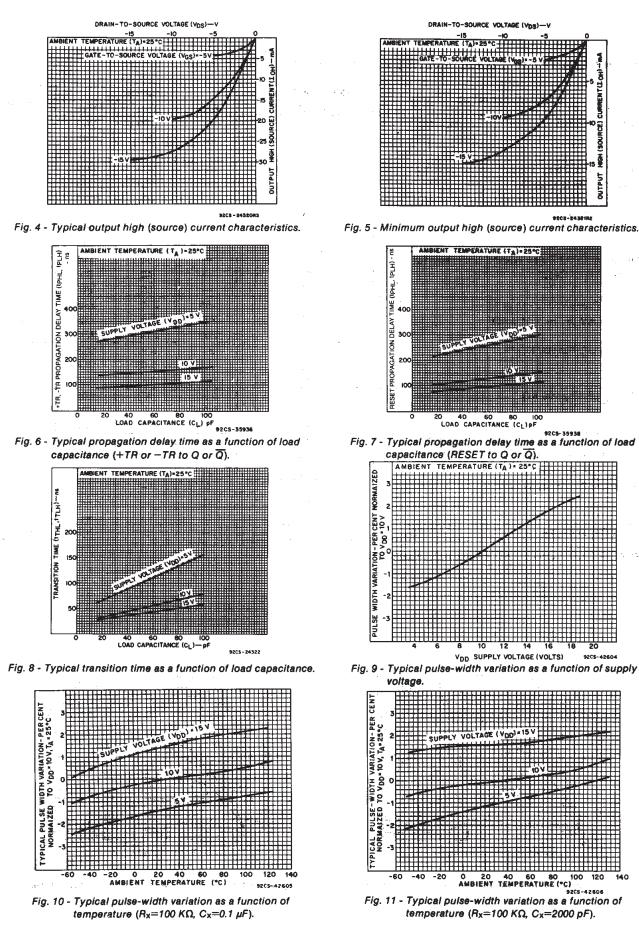


Fig. 3 - Minimum output low (sink) current characteristics.



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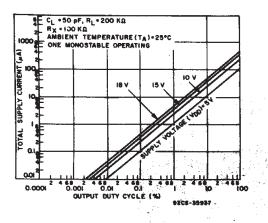
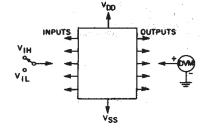


Fig. 12 - Typical total supply current as a function of output duty cycle.







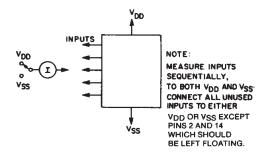
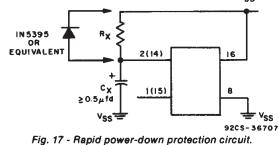
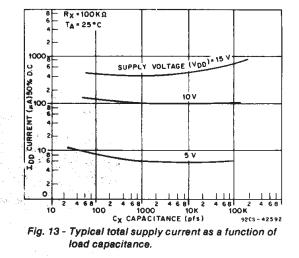


Fig. 15 - Input leakage-current test circuit.

Power-Down Mode

During a rapid power-down condition, as would occur with a power-supply short circuit or with a poorly filtered power supply, the energy stored in C_x could discharge into Pin 2 or 14. To avoid possible device damage in this mode, when C_x is ≥ 0.5 microfarad, a protection diode with a 1-ampere or higher rating (1N5395 or equivalent) and a separate ground return for C_x should be provided as shown in Fig. 17. v_{DD}





NOTE:

1. Test any combination of inputs. 2. When measuring V_{IH} or V_{IL} for Schmitt trigger inputs (+TR, -TR), the input must first be brought to V_{DD} or V_{SS}, respectively, then reduced to the specified limit.

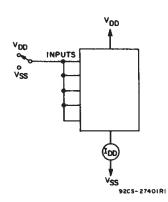


Fig. 16 - Quiescent device current test circuit.

An alternate protection method is shown in Fig. 18, where a 51-ohm current-limiting resistor is inserted in series with C_x . Note that a small pulse width decrease will occur however, and R_x must be appropriately increased to obtain the originally desired pulse width.

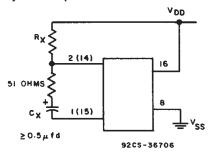
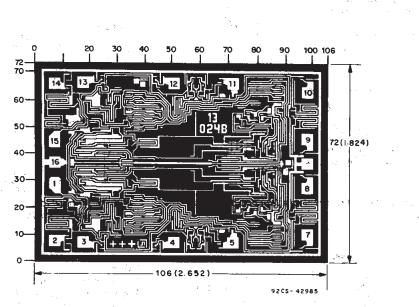


Fig. 18 - Alternate rapid power-down protection circuit.



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch).

Dimensions and pad layout for CD14538BH.



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9055701EA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD14538BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD14538BF	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD14538BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD14538BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD14538BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD14538BMT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD14538BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD14538BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD14538BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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